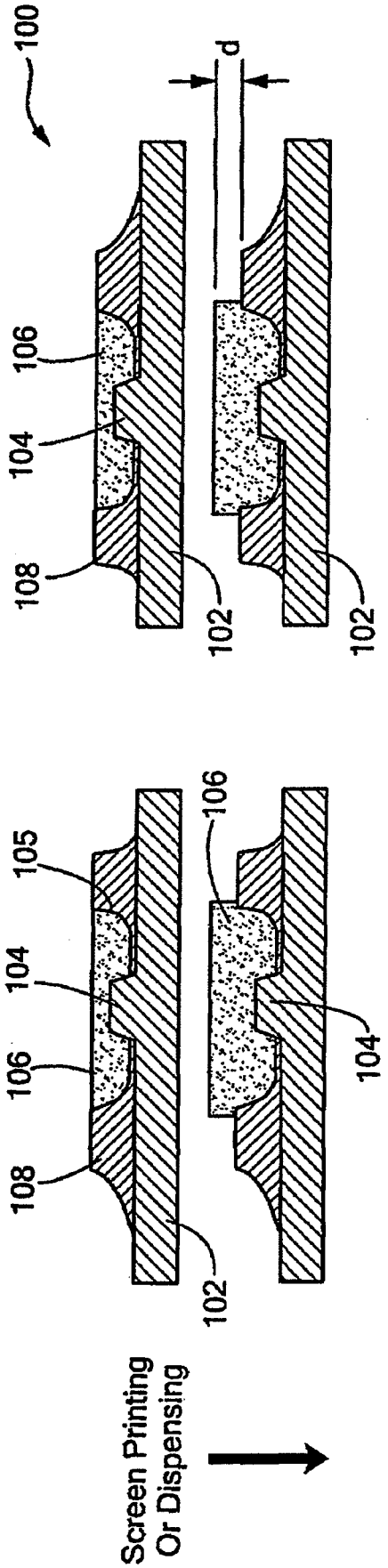

100
d
106
104
108
102
102
105
106
104
106
108
102
104
Screen Printing
Or Dispensing

FIG. 1A

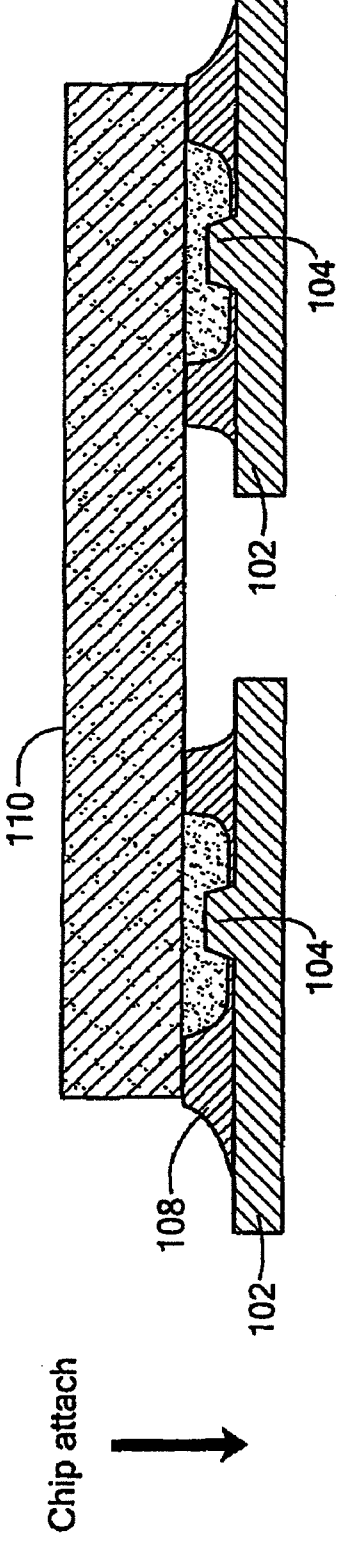

100
104
102
110
104
108
102
Chip attach

FIG. 1B

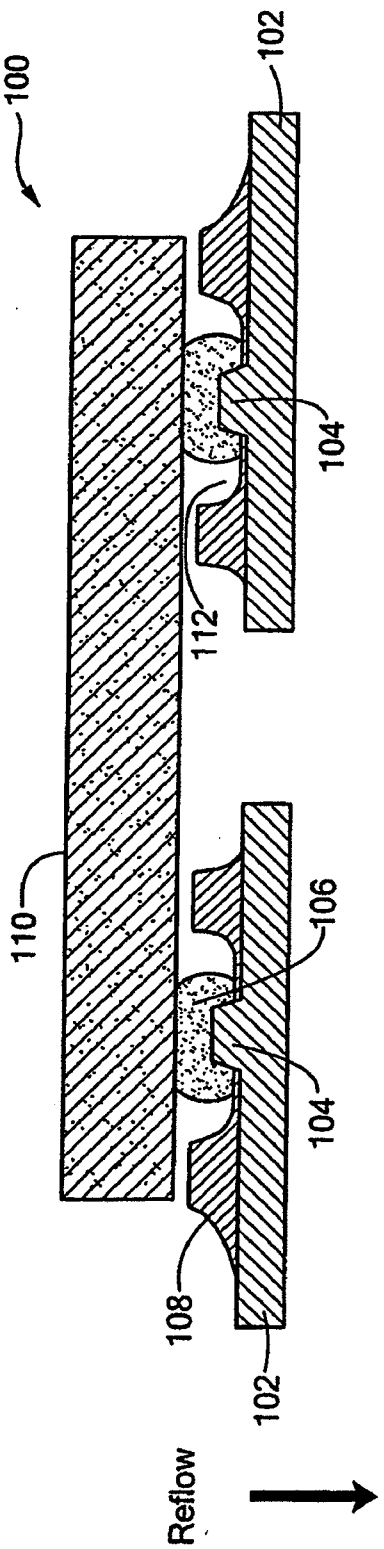

100
102
104
112
110
106
104
108
102
Reflow

FIG. 1C

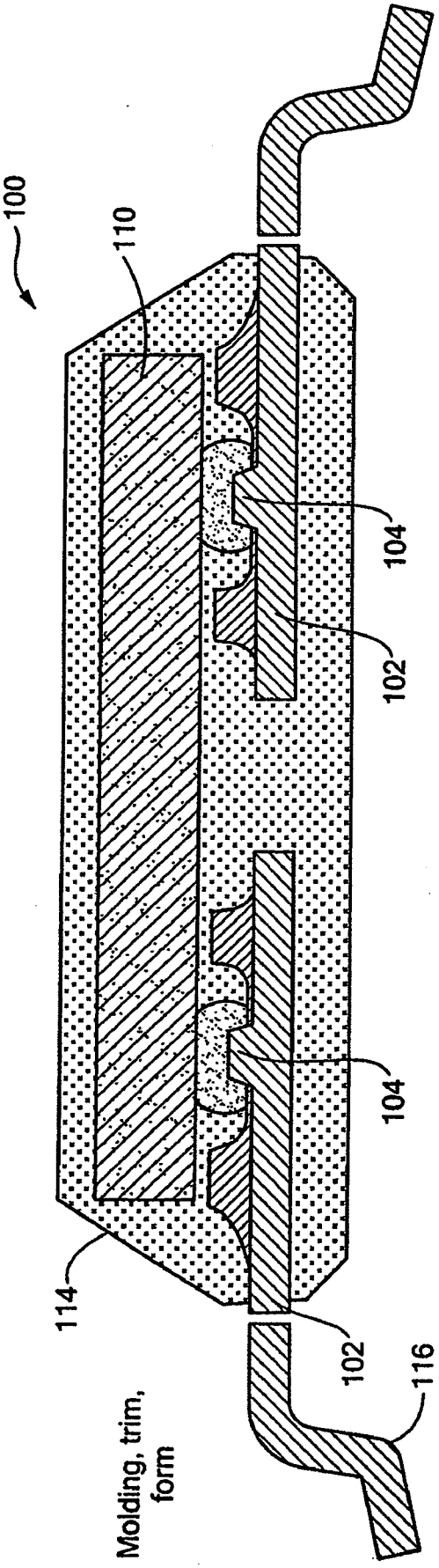
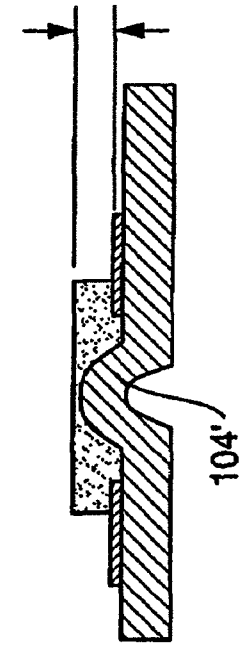
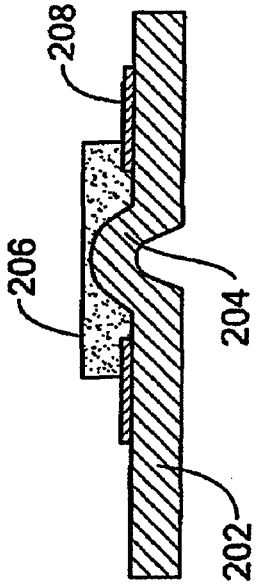

100
110
104
102
104
114
102
116
Molding, trim, form

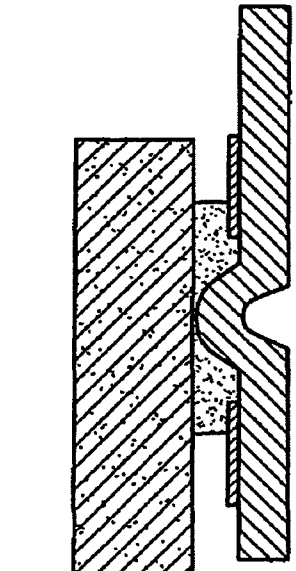
FIG. 1D

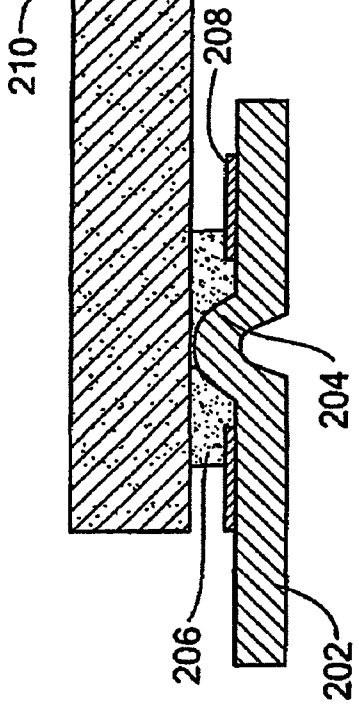




Screen Printing Or Dispensing

FIG. 2A





Chip attach

FIG. 2B

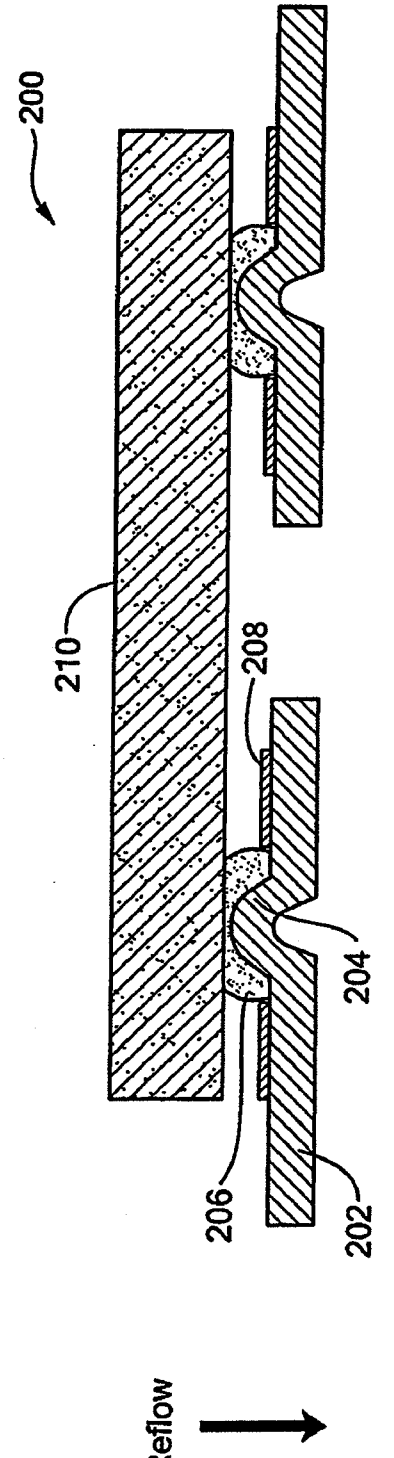

200
210
208
204
206
202
Reflow

FIG. 2C

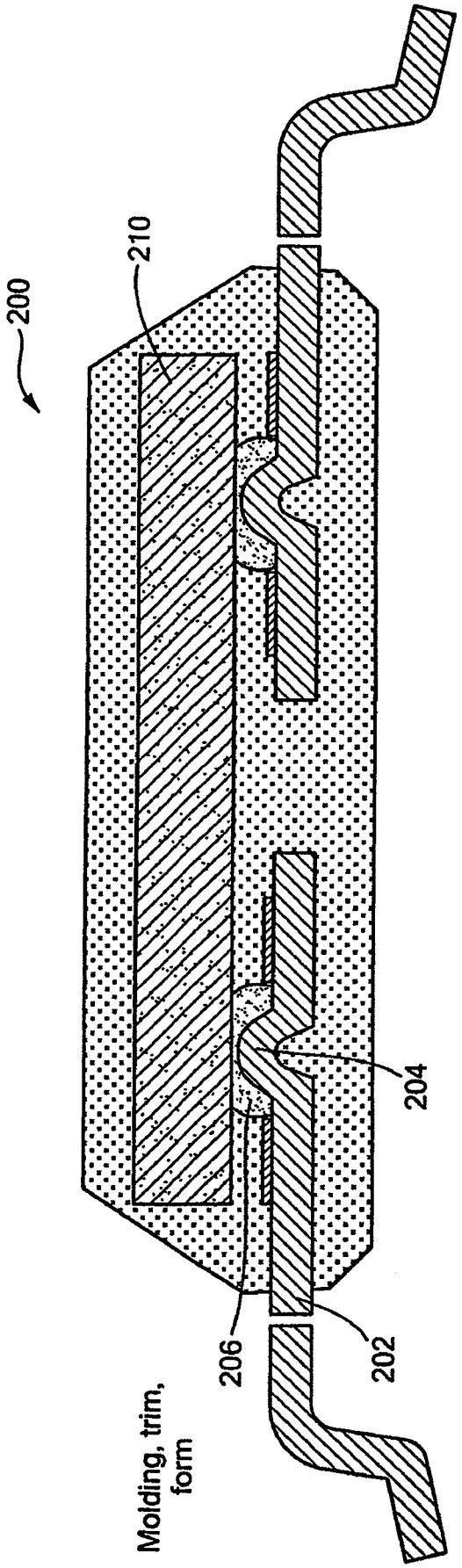

200
210
204
206
202
Molding, trim, form

FIG. 2D

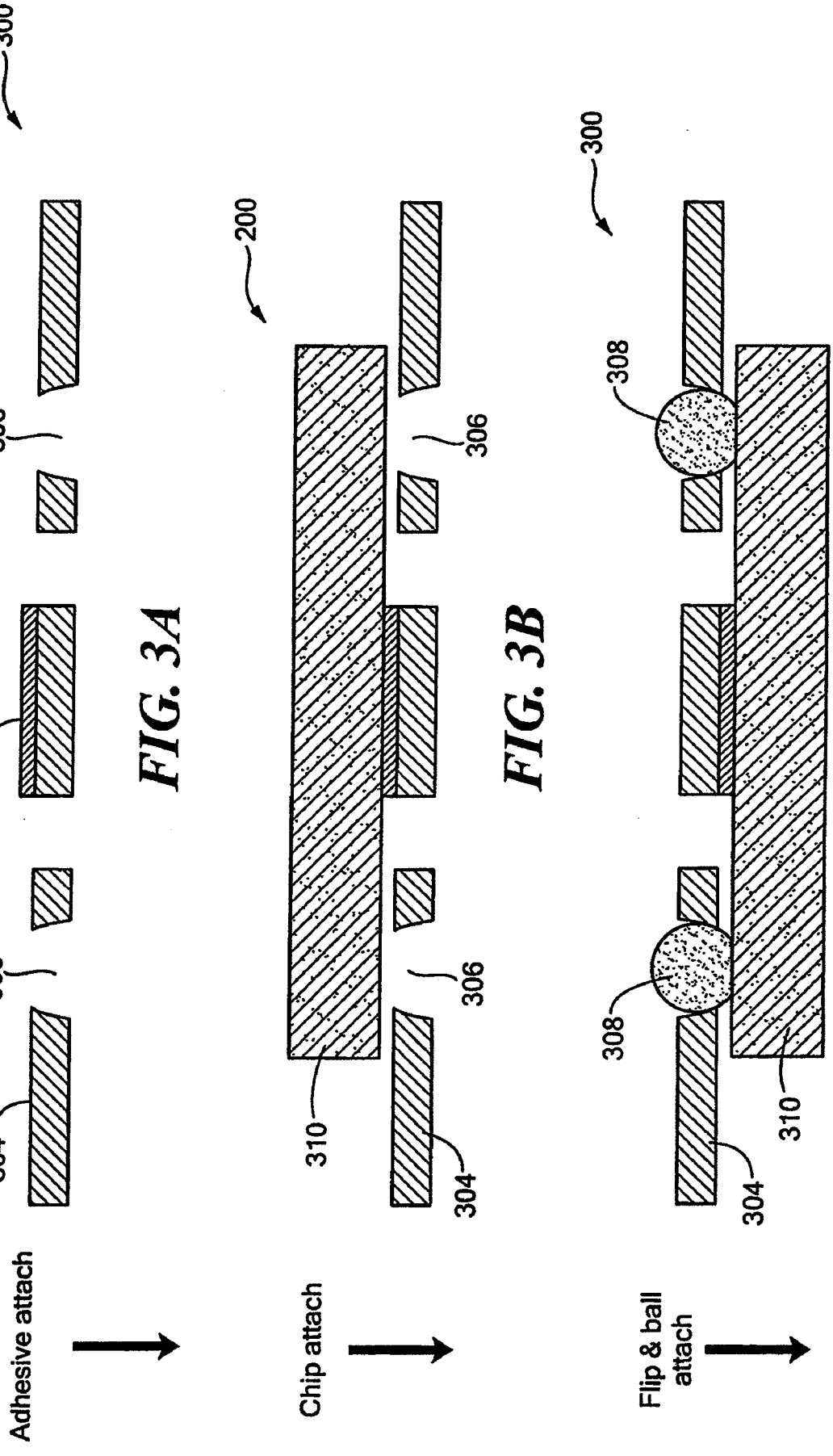


FIG. 3A

FIG. 3B

FIG. 3C

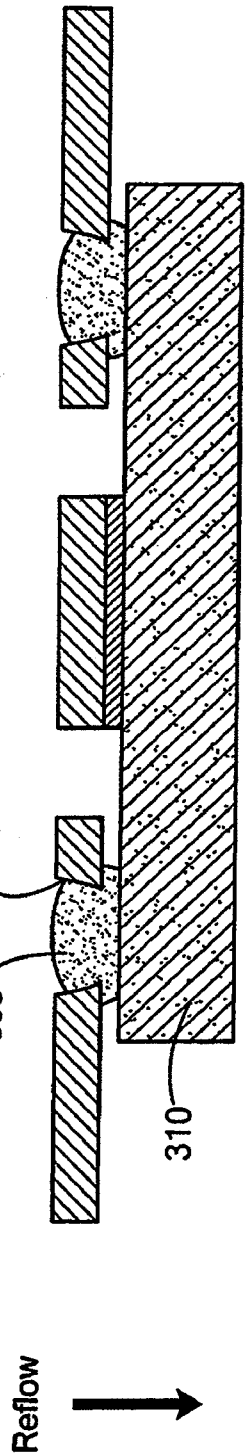


FIG. 3D

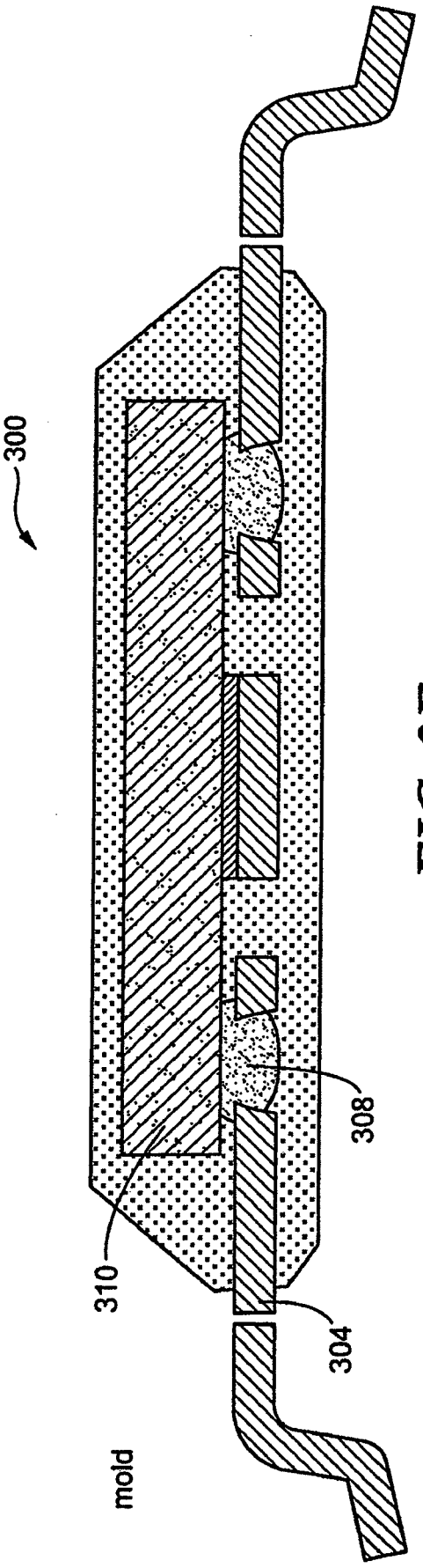


FIG. 3E

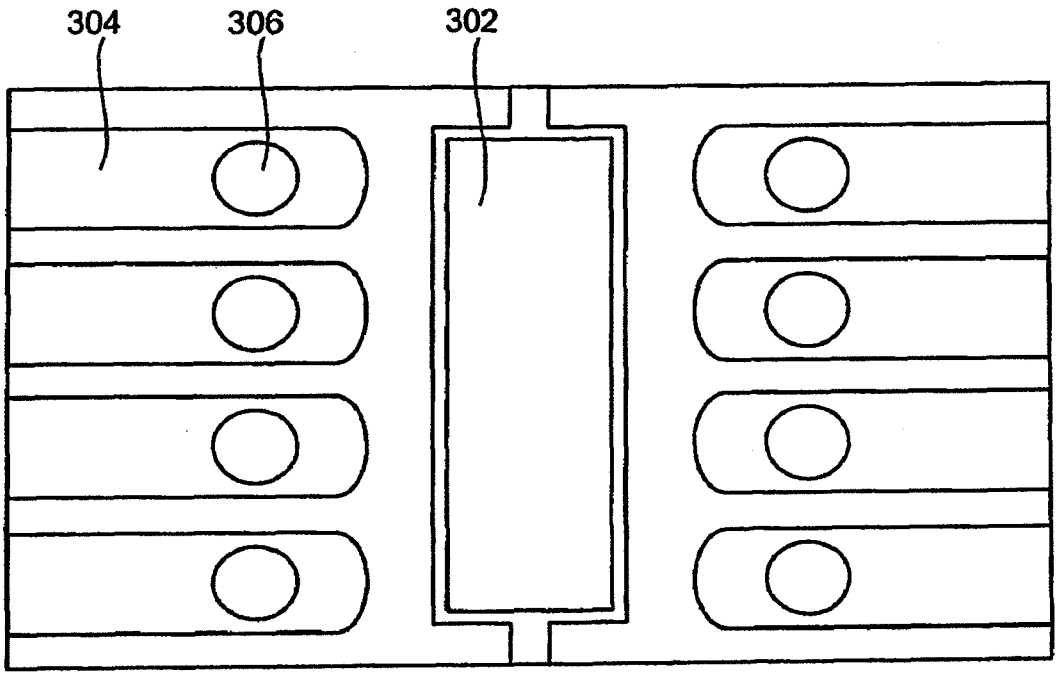


FIG. 3A1

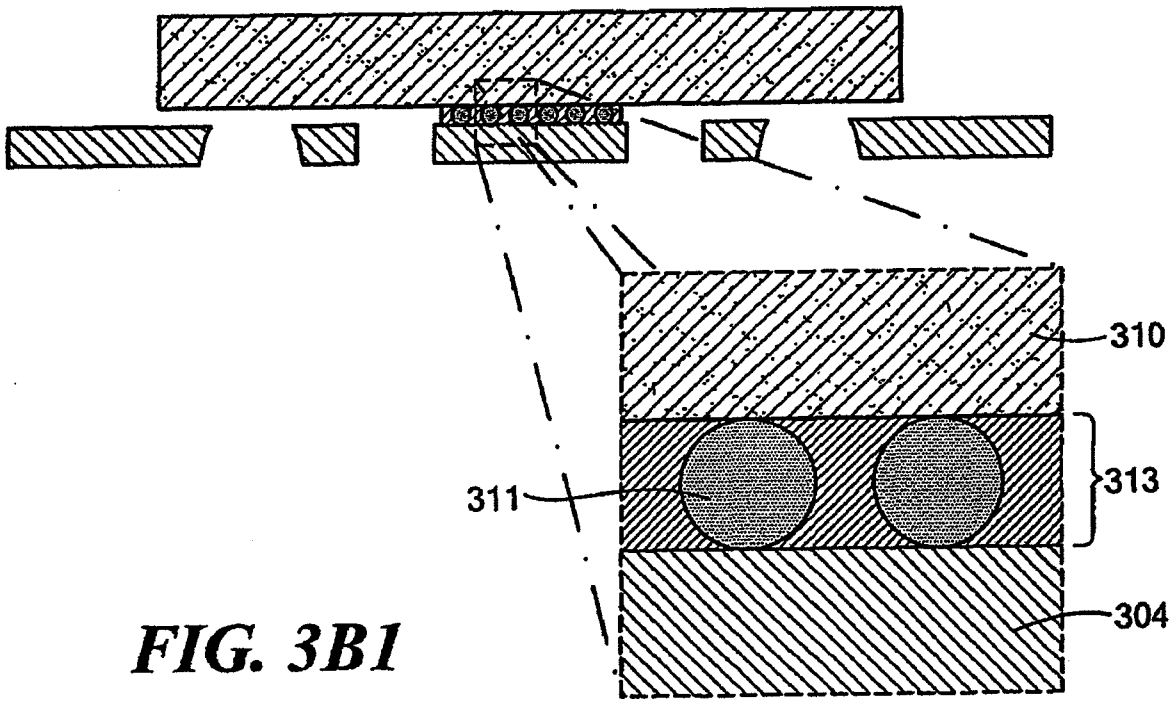


FIG. 3B1

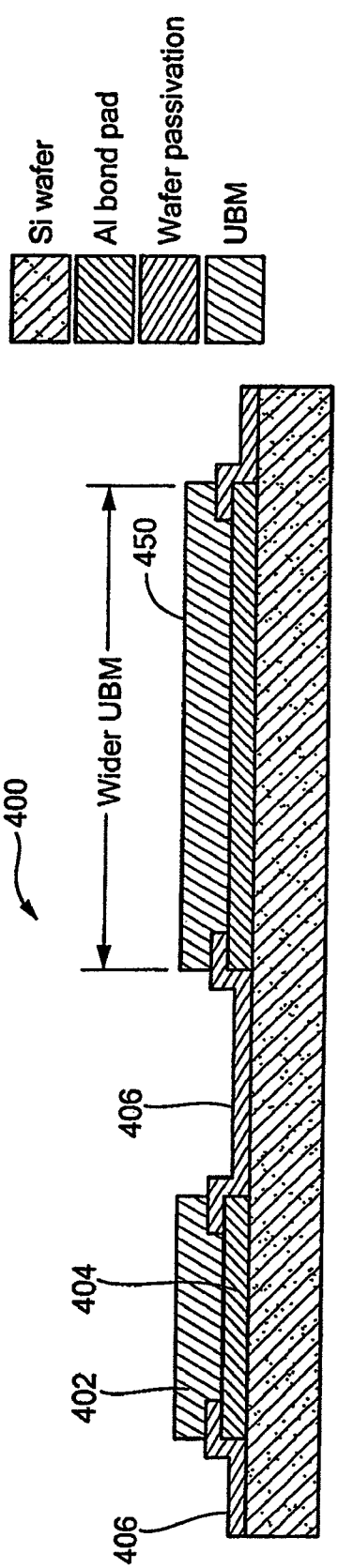

Si wafer
Al bond pad
Wafer passivation
UBM
400
Wider UBM
450
406
404
402
406

FIG. 4

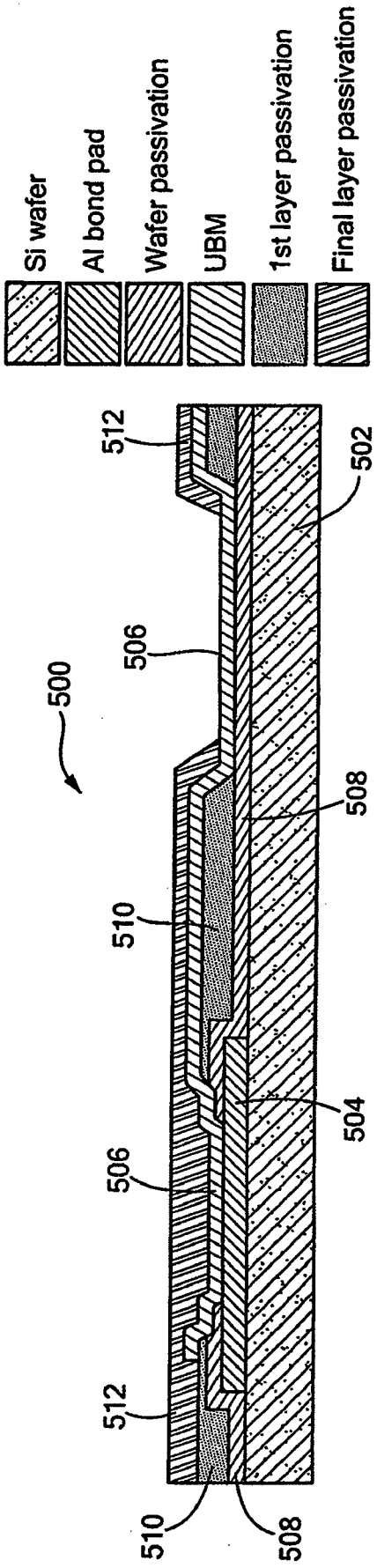

Si wafer
Al bond pad
Wafer passivation
UBM
1st layer passivation
Final layer passivation
500
512
502
506
508
510
504
506
512
510
508

FIG. 5